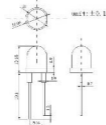
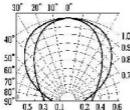


## Package Dimension



## Radiation Diagram



## Features:

- ✓ Built-in 5x Power Chips for up to 100mA Operation
- ✓ Low Power Consumption
- ✓ Longer Life Time
- ✓ I.C. Compatible

## Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Maximum	Unit
DC forward current	$I_f$	100	mA
Peak forward current	$I_{pV}$	200	mA
Pulse width Max. 10ms duty ratio Max. 1/10			
Reverse Voltage	$V_R$	5	V
Power dissipation	$P_D$	400	mW
Operating Temperature	$T_{op}$	$-40 \sim +85$	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	$-40 \sim +100$	$^\circ\text{C}$
Soldering Temperature	$T_{sld}$	260 $^\circ\text{C}$ for 5sec	$^\circ\text{C}$

## Electrical: Optical Characteristics ( $T_a = 25^\circ\text{C}$ )

Item	Symbol	Condition	Min	Typ	Max	Unit
DC forward voltage	$V_f$	$I_f = 100\text{mA}$	2.8	3.8	4.0	V
DC reverse current	$I_R$	$V_R = 5\text{V}$	-	-	100	$\mu\text{A}$
Intensity luminous	$I_v$	$I_f = 100\text{mA}$	12000	-	18000	md
Color Temperature	$C_t$	$I_f = 100\text{mA}$	-	-	10000	K

## Notes:

- All dimensions are in millimeters.
- Clean only in isopropanol, ethanol, Freon TF (or equivalent).
- If forming is required, it must be done before soldering. Form pin leads by securing under 5mm from body and bedding with radio pliers or the equivalent to avoid pressure on resin. When the LED is mounted into a P.C. board, pitch spacing should be aligned to prevent any stress to the resin. Any unsuitable stress applied to resin may break bonding wire in LED, which will cause failure.
- Protruded resin under flange is 1.5mm Max.
- Specifications are subject to change without notice.

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